



SAMPLE RECEIVED FROM:  
Mode3 Group Limited

Date: 1.5.17

SAMPLE DESCRIPTION:  
Black Luxe high density premium recycled foam chip  
underlay – 10mm thick, 90 kg/m<sup>3</sup> density.

1 of 1

**ASTM C518-2010 - Steady –State Thermal Transmission Properties by Means of the Heat Flow Apparatus**

Test Apparatus Used:	Lasercomp Fox 600	Temperature Differential:	20°C
Sample Orientation:	Horizontal	Estimated Uncertainty in Results:	3.9%
Mean Test Temperature:	23°C		

	<b>Specimens</b>	
	<b>1</b>	<b>2</b>
Specimen Thickness (as received) (mm)	9.9	9.9
Specimen Thickness (as tested) (mm)	9.9	9.9
Specimen Density (as tested) (kg/m <sup>3</sup> )	94	94
Test Duration (hrs:mins.)	01:18	01:12
Measured Heat Flux (W/m <sup>2</sup> )	28.0	28.0
Measured Thermal Conductivity (W/m.K)	0.0374	0.0373
Thermal Resistance (m <sup>2</sup> K/W)	0.27	0.27

The calibration of the Heat Flow Apparatus was checked immediately prior to the commencement of the test.

For testing purposes the samples were sandwiched between 2 layers of standard foam sheets. The total thermal resistance of the assembly was measured and the previously measured thermal resistance of the foam subtracted to give the thermal resistance of the product.

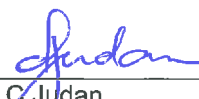
Specimens were tested at a mean of 23°C and a temperature difference of 20°C.

This test was carried out by a sub-contracted laboratory.

**“THIS REPORT APPLIES ONLY TO THE SAMPLES TESTED”**

Samples and their identifying descriptions have been provided by the client unless otherwise stated. NZWTA Ltd makes no warranty, implied or otherwise as to the source of the tested samples. The above results are designed to provide THE CLIENT WITH GUIDANCE INFORMATION ONLY. This document shall not be reproduced except in full.

L A Greer  
Signatory

  
C Judan  
Signatory

26/05/2017